

Resin Composition and Semiconductor Mounting Substrate Obtained by Molding Same

Abstract

5 A resin composition which contains at least constituent elements (A)-(E) described below and wherein the epoxy resin (A) contains 80-100% by mass of a bifunctional epoxy resin and component (D) is contained in an amount of 60-85% by mass relative to 100% by mass of the total mass of the resin composition. This resin
10 composition does not substantially contain a solvent and is in a liquid state at room temperature. (A) an epoxy resin (B) an amine-based curing agent (C) an accelerator that has at least one functional group selected from among a dimethylureide group, an imidazole group and a tertiary amino group (D) silica particles (E) a silane coupling agent Provided is a resin composition which has excellent curability at low
15 temperatures and a sufficiently low linear expansion coefficient after curing. This resin composition does not suffer from warping in cases where applied to a copper thin film and molded, and does not suffer from separation or cracks even if a substrate obtained therefrom is bent. Also provided is a semiconductor mounting substrate which is obtained by molding the resin composition.

20 (No Suitable Figure)